BL3535IR6G42-T8A-850

3.45x3.45mm, Infrared Emitting diode Ceramic Package Top View LED Technical Data Sheet

Features:

- Small SMT ceramic package with high efficiency.
- Very long operating life.
- Low voltage DC operated.
- High radiant intensity.
- Peak Emission Wavelength λp =850nm.
- Instant light (less than 100 ns).
- High reliable.
- The product itself will remain within RoHS compliant Version.
- Double gold thread.
- 99.99% double gold wire welding is more reliable and stable.
- High color consistency, high quality, high lumen.
- Low voltage DC.
- Safer low-voltage DC operation.

Applications:

- Optoelectronic switch.
- Floppy disk drive.
- Free air transmission system.
- Infrared applied system.
- Smoke detector.

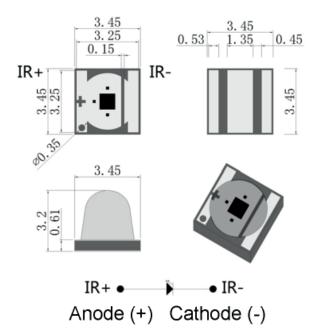
Descriptions:

- The C3535 Infrared Emitting Diode is a high intensity diode.
- The device is spectrally matched with phototransistor, photodiode and infrared receiver module.

Technical Data Sheet

Part No.	Emitting Color	Lens Color
BL3535IR6G42-T8A-850	Infrared	Water Clear

Package Dimensions:



Notes:

1. All dimensions are in millimeters (inches).

- 2. Tolerance is ± 0.25 mm (.010") unless otherwise noted.
- 3. Protruded resin under flange is 1.00mm (.039") max.







Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol	Мах	Unit	
Power Dissipation	Pd	3	W	
Peak Forward Current ^(a)	IFP	1000	mA	
DC Forward Current ^(b)	IF	700	mA	
Electrostatic Discharge (HBM)	ESD	2000	V	
LED Junction Temperature	Tj	120	°C	
Operating Temperature Range	Topr	-40°C to +80°C		
Storage Temperature Range	Tstg	-40°C to +85°C		
Soldering Temperature	Tsld	260°C for 5 seconds		

Notes:

a. Derate linearly as shown in derating curve.

b. Duty Factor = 10%, Frequency = 1 kHz

Electrical Optical Characteristics at Ta=25°C

Parameters	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Radiant Intensity	IE	300	430		mW/sr	IF=700mA
Radiant Flux	Ро	300	500		mW	IF=700mA
Viewing Angle ^(b)	201/2		60		deg.	IF=350mA
Peak Emission Wavelength	λр		850		nm	IF=350mA
Spectral Line Half-Width	Δλ		45		nm	IF=350mA
Forward Voltage	VF	1.4		2.0	V	IF=350mA
Thermal Resistance Junc- tion/ Solder Point	Rth		7		°C/W	IF=350mA
Reverse Current	IR			50	μA	VR=5V

Notes:

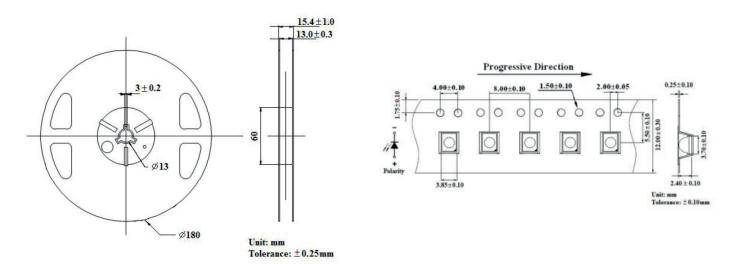
a. 201/2 is the off-axis angle where the luminous intensity is 1/2 the peak intensity

BL3535IR6G42-T8A-850 3.45x3.45mm, Infrared Emitting diode Ceramic Package Top View LED Technical Data Sheet

BENTEX

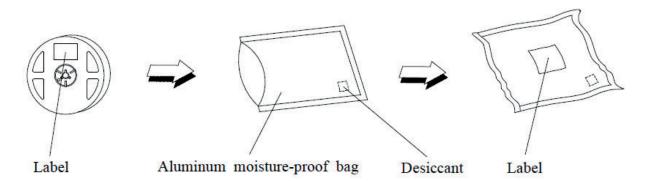
Reel and Tape Dimensions:

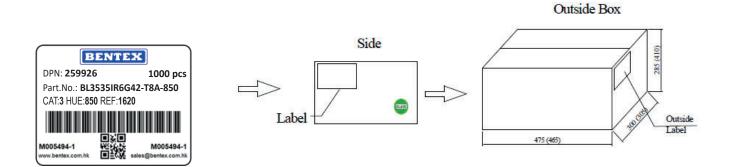
Loaded quantity 1000 pcs per reel.



Packing & Label Specifications:

Moisture Resistant Packaging:





Spec No.: C3535 Issue No.: G-Rev-5 BENTEX Limited Copyright © 2021 BENTEX Limited All Rights Reserved Date: 16-Sep-2021 E-mail: sales@bentex.com.hk http://www.bentex.com.hk Page: 4 / 5



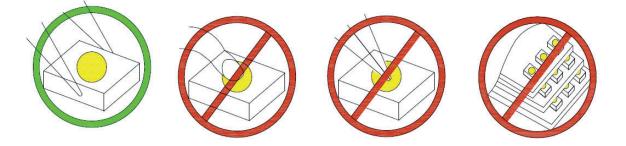
CAUTIONS

1. Handling Precautions:

1.1. Handle the component along the side surfaces by using forceps or appropriate tools.

1.2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

1.3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

2. Storage

2.1. Do not open moisture proof bag before the products are ready to use.

2.2. Before opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

2.3. The LEDs should be used within a year.

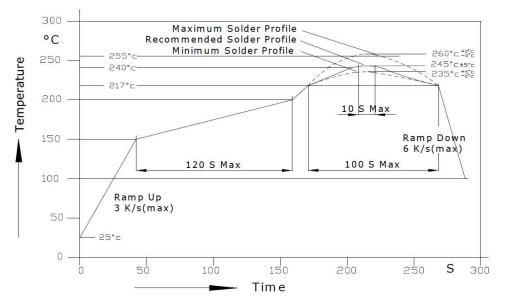
2.4. After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

2.5. The LEDs should be used within 24 hours after opening the package.

2.6. If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 65±5°C for 24 hours.

3. Soldering Condition

3.1. Pb-free solder temperature profile



Recommended soldering conditions:

Spec No.: C3535 Issue No.: G-Rev-5 BENTEX Limited Copyright © 2021 BENTEX Limited All Rights Reserved Date: 16-Sep-2021 E-mail: sales@bentex.com.hk http://www.bentex.com.hk Page: 5 / 5

BL3535IR6G42-T8A-850



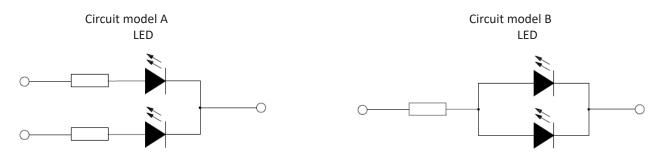
- 3.2. Reflow soldering should not be done more than two times.
- 3.3. When soldering, do not put stress on the LEDs during heating.
- 3.4. After soldering, do not warp the circuit board.
- 3.5. Recommended soldering conditions:

Soldering iron		Reflow soldering		
Temperature	300°C Max.	Pre-heat	150-200°C Max.	
		Pre-heat Time	120 sec. Max.	
Soldering Time	3 sec. Max. (one time only)	Solder Wave	260°C Max.	
		Soldering Time	10 sec. Max.(Max. two times).	

3.6. Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations. However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

4. Drive Method

4.1. An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



(A) Recommended circuit

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

Terms and conditions for the usage of this document

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.

2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.

3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Luckylight will not be responsible for any subsequent issues.

4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Luckylight representative for further assistance.

5. The contents and information of this document may not be reproduced or re-transmitted without permission by Luckylight.